



Flex Area 1	Rigid Area	Flex Area 2	Flex Area 2 with Stiffener
	Paste Stencil, GTP		
	Solder Mask, 1.0mil, GTS		
	Layer 1, 0.5 oz base, 0.7mil, Copper, GTL		
	Dielectric, 2.75mil, Prepreg 1080NF IT 180A		
	Layer 2, 0.7mil, Copper, G1		
	Dielectric, 6.0mil, FR4 0.006 IT 180A		Core, 12 mil, 0.12 IT 180A
Flex Coverlay Top, 2.0mil, MCL Plus 110	Layer 3, 0.7mil, Copper, G2		Flex Bond–Ply, 1.0mil, PSA
Layer 4, 0.7mil, Copper, G3	Dielectric, 5.5mil, Prepreg 1080NF IT 180A	Flex Coverlay Top, 2.0mil, MCL Plus 110	Flex Coverlay Top, 2.0mil, MCL Plus 110
Dielectric (Core), 2.0mil, Polyimide RF775 0.002 H/H	Layer 4, 0.7mil, Copper, G3	Layer 4, 0.7mil, Copper, G3	Layer 4, 0.7mil, Copper, G3
Layer 5, 0.7mil, Copper, G4	Dielectric (Core), 2.0mil, Polyimide RF775 0.002 H/H	Dielectric (Core), 2.0mil, Polyimide RF775 0.002 H/H	Dielectric (Core), 2.0mil, Polyimide RF775 0.002 H/H
Flex Coverlay Bottom, 2.0mil, MCL Plus 110	Layer 5, 0.7mil, Copper, G4	Flex Coverlay Bottom, 2.0mil, MCL Plus 110	Flex Coverlay Bottom, 2.0mil, MCL Plus 110
	Dielectric, 5.5mil, Prepreg 1080NF IT 180A		Flex Bond–Ply, 1.0mil, PSA
	Layer 6, 0.7mil, Copper, G5		Core, 12 mil, 0.12 IT 180A
	Dielectric, 6.0mil, FR4 0.006 IT 180A		
	Layer 7, 0.7mil, Copper, G6		
	Dielectric, 2.75mil, Prepreg 1080 NFIT 180A		
	Layer 8, 0.5 oz base, 0.7mil, Copper, GBL		
	Solder Mask, 1.0mil, GTS		
	Paste Stencil, GTP		

- 1. Board Technology:
 - A. Fabricate Rigid-Flex PCB in accordance with IPC-6013 and IPC 2223, Type 4, Class 3
 - B. All materials must be compliant with the European Union RoHS 2 directive, 011/65/EU
 - C. Maximum overall rigid thickness shall not exceed 925um. This is measured over finished plated surfaces.
 - D. Finished hole size unless noted should be +/- 3 mil (0.076mm)
 - E. Finish shall be ENIG
 - 1. Electroless nickel thickness in accordance with IPC-4552
 - 2. Immersion Gold thickness in accordance with IPC-4552
 - F. Soldermask shall be Blue on both sides in accordance with IPC-SM-840 Class H.
 - G. Silkscreen shall be White on both sides
- 2. Certificate of Conformity:
 - A. Complete description of the item with revision
 - B. Lot and Date Code
 - C. Delivered quantity
 - D. RoHS compliance
 - E. Remark/Exception as concession note
 - F. Name of the responsible person with signature and date
- 3. Inspection Report:
 - A. Type of used base material and metallizations processes
 - 1. Brand, reference and lot number of used base material
 - 2. Used metallization and processes (chemical/galvanic) on Cu, Ni and Au
 - B. Visual checks and results:
 - 1. Aspect (contamination, color, asperities, residues, mark, scraping, repair, etc.)
 - 2. Open, short-circuit, etching non-conformities
 - 3. Metallization adherence in accordance with IPC-TM-650 -- Method 2.4.1
 - 4. Solder mask adherence in accordance with IPC-TM-650 -- Method 2.4.28.1
 - C. Dimensional checks and results:
 - 1. Length and width of Strip
 - 2. Length, width and total thickness of circuit
 - 3. Diameter of index holes.
 - 4. The thickness of nickel and gold metallizations shall be measured in accordance with IPC-4552 and a report of the measurements shall be provided.
 - D. Electrical Test:
 - 1. Continuity and shorts 100% tested.
 - E. Micro section report:
 - 1. Configuration of stack-up with measurements of different thicknesses
 - 2. Thickness of Copper metallization.
 - F. Solderability test report:
 - 1. Result of the solderability test according to ANSI/J-STD-003 -- Category 2 Test A -Hand Dipped

BOARD CHARACTERISTICS

Copper Layer Count:	8	Board Thickness:	1.4100 mm
Board overall dimensions:	84.0000 mm x 94.0000 mm		
Min track/spacing:	0.1500 mm / 0.1500 mm	Min hole diameter:	0.1000 mm
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

COSMIIC

Sheet:
File: PM1C_Rev_1.kicad_pcb

Title: PM1C PCB Fabrication Drawing

Size: B	Date: 2024-07-25	Rev: 1
KiCad E.D.A. 8.0.2		Id: 1/1